



PRODUCT BULLETIN # 20736

Generic Copy

Issue Date: 15-Jan-2015

TITLE: New Enlarged Clip Implementation in 30V Trench 6 SO8FL

PROPOSED FIRST SHIP DATE: 19-Jan-2015

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Manufacturing Assembly

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or Jason Jeong <Jason.Jeong@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customers that it is fanning out an improved clip design used in the Assembly of the S08-FL package for 30V Trench 6 technology for better thermal performance. All new product releases currently incorporate this type of clip and products listed in this product bulletin are being converted after the proposed ship date. The new clip design enlarges the surface area contact to the source and does not require any modifications to the assembly processes or flows.

List of affected General Parts:

NTMFS4C05NT1G	NTMFS4C56NT1G	NTMFS4C800NT1G
NTMFS4C05NT3G	NTMFS4C56NT3G	NTMFS4C50NT1G
NTMFS4C55NT1G	NTMFS4C08NT1G	NTMFS4C50NT3G
NTMFS4C55NT3G	NTMFS4C08NT3G	NTMFS4C13NT1G
NTMFS4C705NT1G	NTMFS4C58NT1G	NTMFS4C13NT3G
NVMFS4C05NT1G	NTMFS4C58NT3G	NTMFS4C53NT1G
NVMFS4C05NT3G	NTMFS4C09NT1G	NTMFS4C53NT3G
NVMFS4C05NWFT1G	NTMFS4C09NT3G	NTMFS4C35NT1G
NVMFS4C05NWFT3G	NTMFS4C59NT1G	NTMFS4C35NT3G
NTMFS4C06NT1G	NTMFS4C59NT3G	NTMFS4C75NT1G
NTMFS4C06NT3G	NTMFS4C10NT1G	NTMFS4C75NT3G
NTMFS4C760NT1G	NTMFS4C10NT3G	